



I_D (Silicon Limited)

17 A

		Conditions	Value	Unit
		T _C	17	A
		T _C	11	A
	V	-	65	V
		-	20	V
Pulsed Drain Current	I _{DM}	-	180	A
		L=0.1mH, T _C	31	mJ
Power Dissipation		T _C	3.1	W
Operating and Storage Temperature	T _J , T _{stg}	-	-55 to150	

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Lead	R _{JL}	25	
Thermal Resistance Junction-Ambient (steady state)	R _{JA}	40	
		75	

Electrical Characteristics at T_j ! a b bb "
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250 \text{ A}$	65	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250 \text{ A}$	2.0	2.7	4.0	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS}=0V, V_{DS}=60V, T_j$	-	-	1	A
		$V_{GS}=0V, V_{DS}=60V, T_j$	-	-	100	
Gate to Source Leakage Current	I_{GSS}	$V_{GS} \quad \quad \quad V_{DS}=0V$	-	-	100	nA
Drain to Source on Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$	-	4.7	5.7	m
Transconductance	g_{fs}	$V_{DS}=5V, I_D=20A$	-	50	-	S
Gate Resistance	R_G	$V_{GS}=0V, V_{DS} \text{ Open}, f=1\text{MHz}$	-	1.2	-	

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=30V, f=1\text{MHz}$	-	2373	-	pF
Output Capacitance	C_{oss}		-	769	-	
Reverse Transfer Capacitance	C_{rss}		-	45	-	
Total Gate Charge	$Q_g(10V)$	$V_{DD}=30V, I_D=20A, V_{GS}=10V$	-	41	-	nC
Gate to Source Charge	Q_{gs}		-	10	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	10	-	
Turn on Delay Time	$t_{d(on)}$	$V_{DD}=30V, I_D=20A, V_{GS}=10V, R_G=10 \quad \quad \quad$	-	11	-	ns
Rise time	t_r		-	7	-	
Turn off Delay Time	$t_{d(off)}$		-	35	-	
Fall Time	t_f		-	9	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_F=30A$	-	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=30V, I_F=20A, di_F/dt=400A/ \text{ s}$	-	35	-	ns
Reverse Recovery Charge	Q_{rr}		-	88	-	nC

Fig 1. Typical Output Characteristics

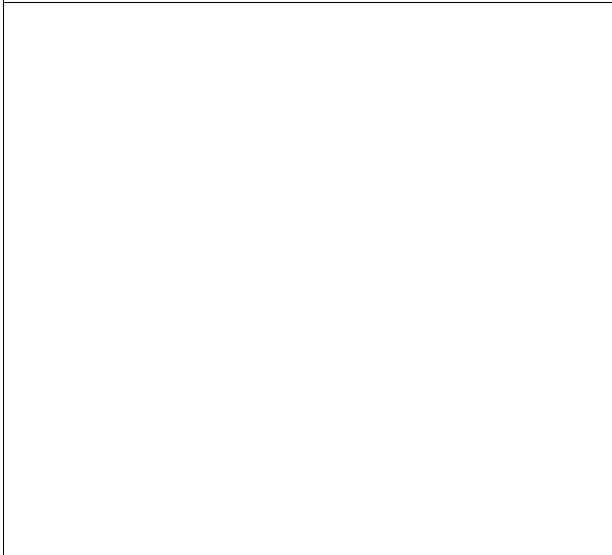


Figure 2. On-Resistance vs. Gate-Source Voltage

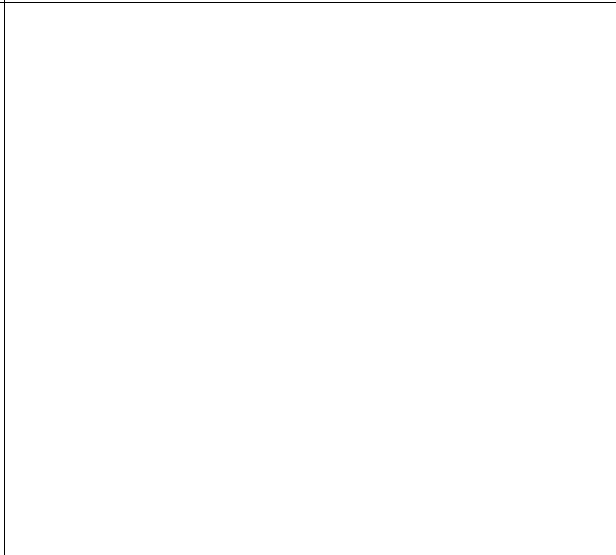


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

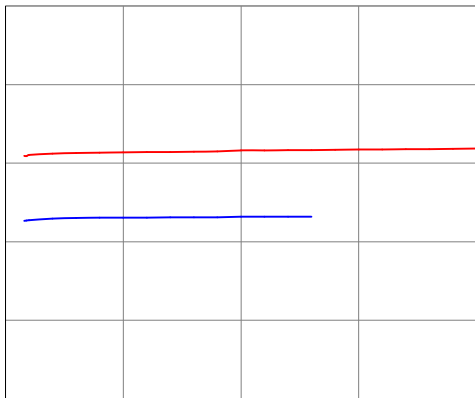


Figure 4. Normalized On-Resistance vs. Junction Temperature



Figure 5. Typical Transfer Characteristics

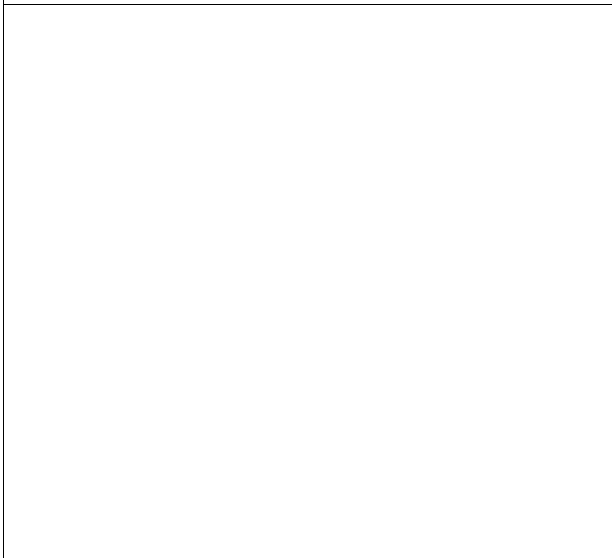
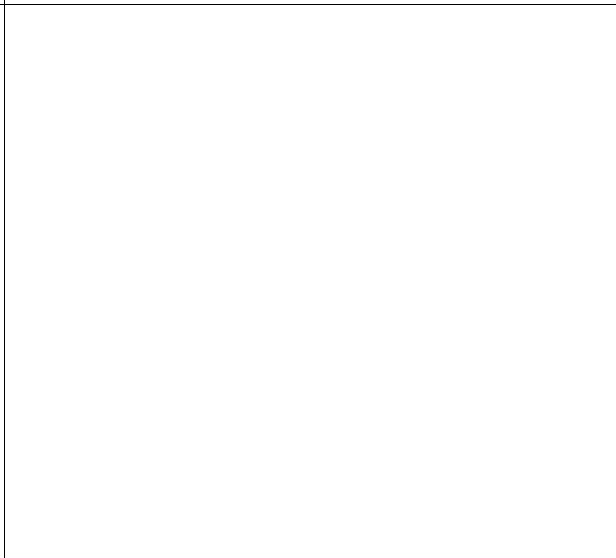
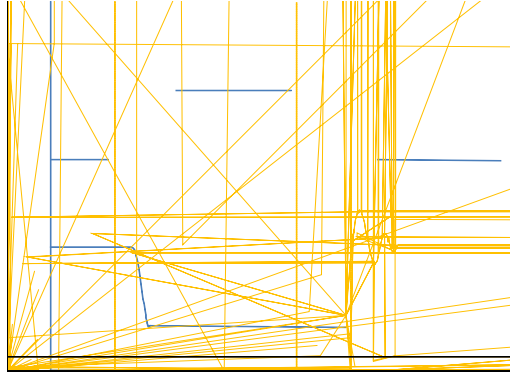
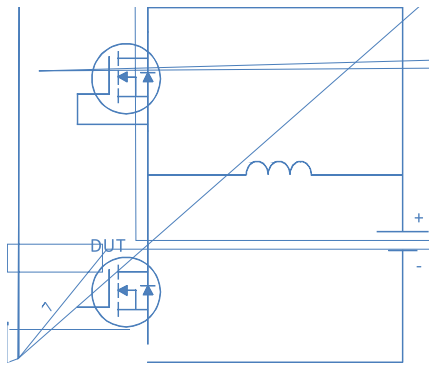


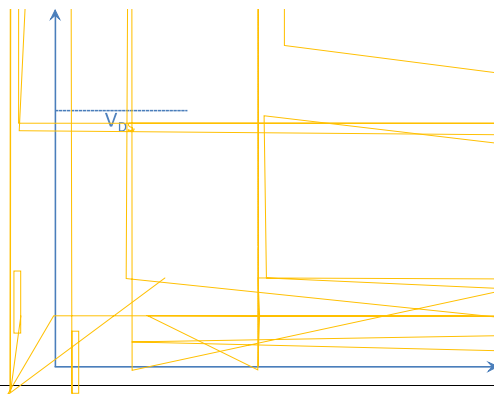
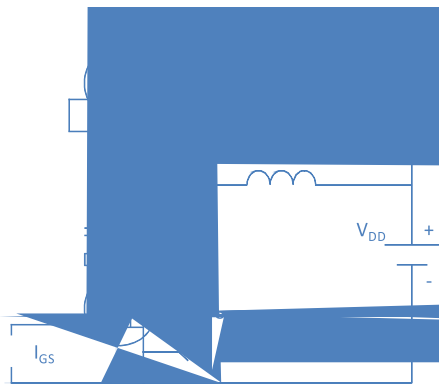
Figure 6. Typical Source-Drain Diode Forward Voltage



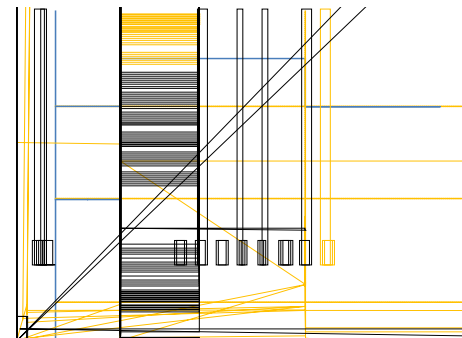
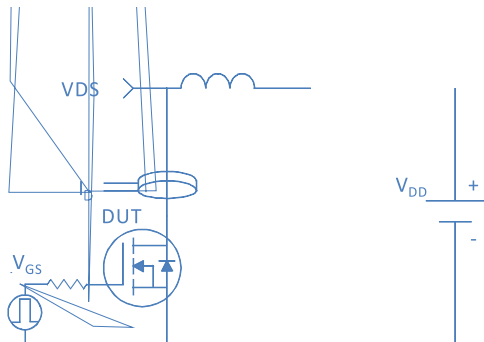
Inductive switching Test



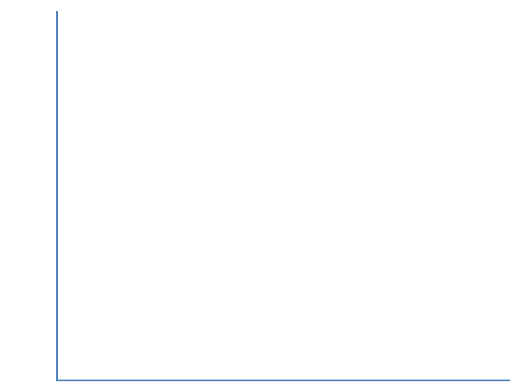
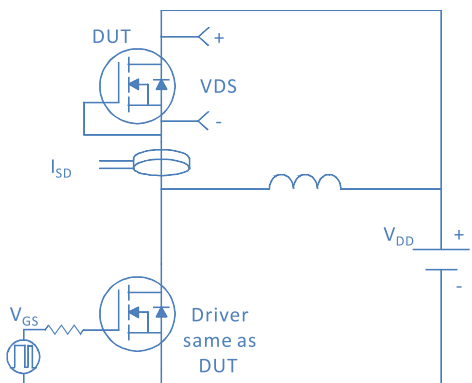
Gate Charge Test

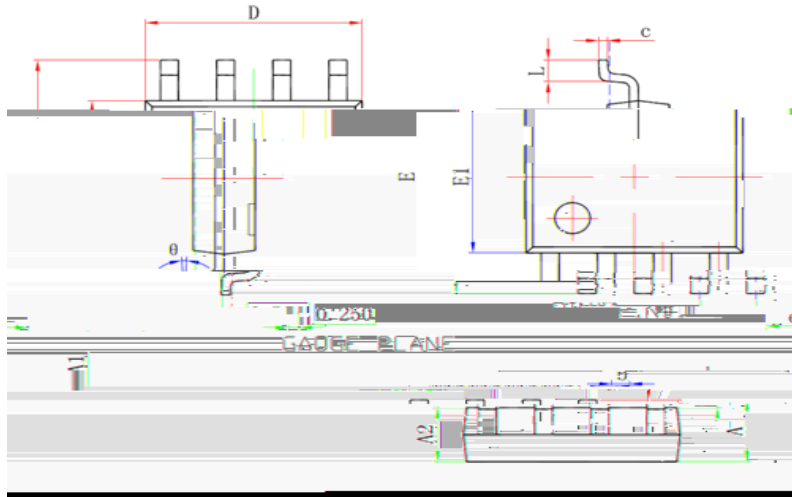


Uclamped Inductive Switching (UIS) Test



Diode Recovery Test



Package Outline
SOIC-8, 8 leads


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.250	1.650	0.049	0.065
b	0.310	0.510	0.012	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (SBC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.031
theta	0°	8°	0°	8°